

Material Content Data Sheet

Sales Product Name	IM12S60EA2	**Issued**	28. March 2025
MA#	MA006150705		
Package	PG-MDIP-24-63	**Weight:**	6926.91 mg

Construction Element	Material group	Materials	CAS if applicable	Weight [mg]	Average mass [%]	Sum [%]	Average mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	6.694	0.10	0.10	966	966
chip_2	inorganic material	siliconcarbide	409-21-2	2.646	0.04	0.04	382	382
chip_3	inorganic material	siliconcarbide	409-21-2	2.646	0.04	0.04	382	382
chip_4	inorganic material	siliconcarbide	409-21-2	2.646	0.04	0.04	382	382
chip_5	inorganic material	siliconcarbide	409-21-2	2.646	0.04	0.04	382	382
chip_6	inorganic material	siliconcarbide	409-21-2	2.646	0.04	0.04	382	382
chip_7	inorganic material	siliconcarbide	409-21-2	2.646	0.04	0.04	382	382
leadframe	inorganic material	phosphorus	7723-14-0	0.390	0.01		56	
	non noble metal	iron	7439-89-6	1.300	0.02		188	
	non noble metal	copper	7440-50-8	1298.097	18.74	18.77	187399	187643
wire	noble metal	gold	7440-57-5	0.609	0.01		88	
	non noble metal	aluminium	7429-90-5	52.092	0.75	0.76	7520	7608
encapsulation	organic material	carbon black	1333-86-4	30.734	0.44		4437	
	plastics	epoxy resin	-	384.169	5.55		55460	
	inorganic material	silicondioxide	60676-86-0	3426.785	49.46	55.45	494706	554603
leadfinish	non noble metal	tin	7440-31-5	41.697	0.60	0.60	6020	6020
plating	non noble metal	nickel	7440-02-0	2.741	0.04	0.04	396	396
solder	non noble metal	antimony	7440-36-0	0.377	0.01		54	
	noble metal	silver	7440-22-4	0.943	0.01		136	
	non noble metal	tin	7440-31-5	2.453	0.04	0.06	354	544
glue	inorganic material	amorphous silica	7631-86-9	0.339			49	
	plastics	acrylic resin	-	0.667	0.01		96	
	noble metal	silver	7440-22-4	1.313	0.02	0.03	189	334
smd	inorganic material	silicondioxide	60676-86-0	0.003			1	
	noble metal	gold	7440-57-5	0.012			2	
	noble metal	palladium	7440-05-3	0.019			3	
	noble metal	silver	7440-22-4	0.030			4	
	organic material	ethyl cellulose	9004-57-3	0.024			4	
	organic material	DEGBE	112-34-5	0.105			15	
	inorganic material	cobalt(II)oxide	1307-96-6	0.200			29	
	inorganic material	copperoxide	1317-38-0	0.576	0.01		83	
	inorganic	manganesedioxide	1313-13-9	0.658	0.01	0.02	95	236

	material							
pcb metal	non noble metal	copper	7440-50-8	21.446	0.31	0.31	3096	3096
pcb plastic	miscellaneous	miscellaneous	-	26.649	0.38		3847	
	inorganic material	silicondioxide	60676-86-0	42.639	0.62		6156	
	organic material	Poly[phenylglycidylether-coformaldehyde]	28064-14-4	50.634	0.73		7310	
	inorganic material	glass fibre	-	146.572	2.12	3.85	21160	38473
pcb plating	noble metal	gold	7440-57-5	0.066			10	
	non noble metal	nickel	7440-02-0	3.029	0.04	0.04	437	447
dcb ceramic	inorganic material	zirconium dioxide	1314-23-4	7.862	0.11		1135	
	inorganic material	aluminum nitride	24304-00-5	697.271	10.07	10.18	100661	101796
dcb metal	non noble metal	copper	7440-50-8	661.840	9.55	9.55	95546	95546
deviation	< 10%				Sum in total:	100.00		1000000

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